



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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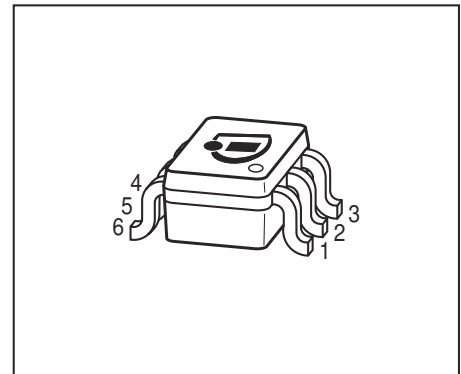
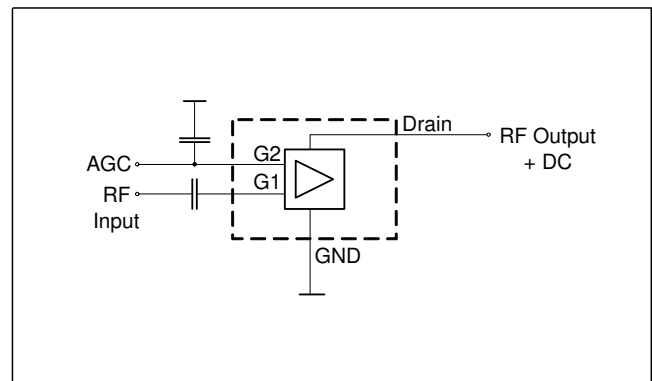
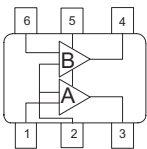
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DUAL N-Channel MOSFET Tetrode

- Low noise gain controlled input stages of UHF- and VHF-tuners with 5V supply voltage
- Two AGC amplifiers in one single package
- Integrated stabilized bias network
- Integrated gate protection diodes
- High gain, low noise figure
- Improved cross modulation at gain reduction
- High AGC-range


**BG3230
BG3230R**


ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Type	Package	Pin Configuration						Marking
BG3230	SOT363	1=G1*	2=G2	3=D*	4=D**	5=S	6=G1**	KBs
BG3230R	SOT363	1=G1*	2=S	3=D*	4=D**	5=G2	6=G1**	KIs

* For amp. A; ** for amp. B

180° rotated tape loading orientation available

Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	8	V
Continuous drain current	I_D	25	mA
Gate 1/ gate 2-source current	$\pm I_{G1/2SM}$	1	
Gate 1/ gate 2-source voltage	$\pm V_{G1/G2S}$	6	V
Total power dissipation	P_{tot}	200	mW
Storage temperature	T_{stg}	-55 ... 150	°C
Channel temperature	T_{ch}	150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Channel - soldering point ¹⁾	R_{thchs}	≤ 280	K/W

Electrical Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

DC Characteristics

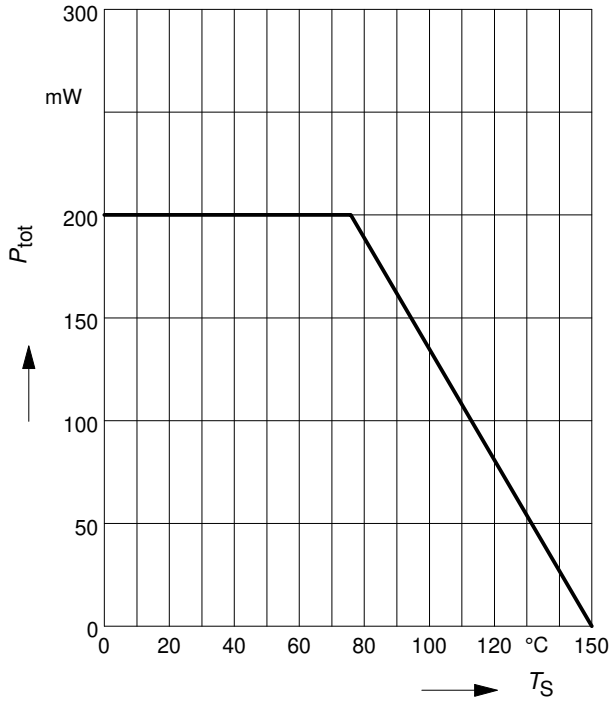
Drain-source breakdown voltage $I_D = 100 \mu A, V_{G1S} = 0, V_{G2S} = 0$	$V_{(BR)DS}$	12	-	-	V
Gate1-source breakdown voltage $+I_{G1S} = 10 mA, V_{G2S} = 0, V_{DS} = 0$	$+V_{(BR)G1SS}$	6	-	15	
Gate2 source breakdown voltage $\pm I_{G2S} = 10 mA, V_{G1S} = 0, V_{DS} = 0$	$\pm V_{(BR)G2SS}$	6	-	15	
Gate1-source leakage current $V_{G1S} = 6 V, V_{G2S} = 0$	$+I_{G1SS}$	-	-	50	μA
Gate 2 source leakage current $\pm V_{G2S} = 6 V, V_{G1S} = 0, V_{DS} = 0$	$\pm I_{G2SS}$	-	-	50	nA
Drain current $V_{DS} = 5 V, V_{G1S} = 0, V_{G2S} = 4 V$	I_{DSS}	-	-	100	μA
Operating current (selfbiased) $V_{DS} = 5 V, V_{G2S} = 4 V$	I_{DSO}	-	13	-	mA
Gate2-source pinch-off voltage $V_{DS} = 5 V, I_D = 100 \mu A$	$V_{G2S(p)}$	-	1	-	V

¹For calculation of R_{thJA} please refer to Application Note Thermal Resistance

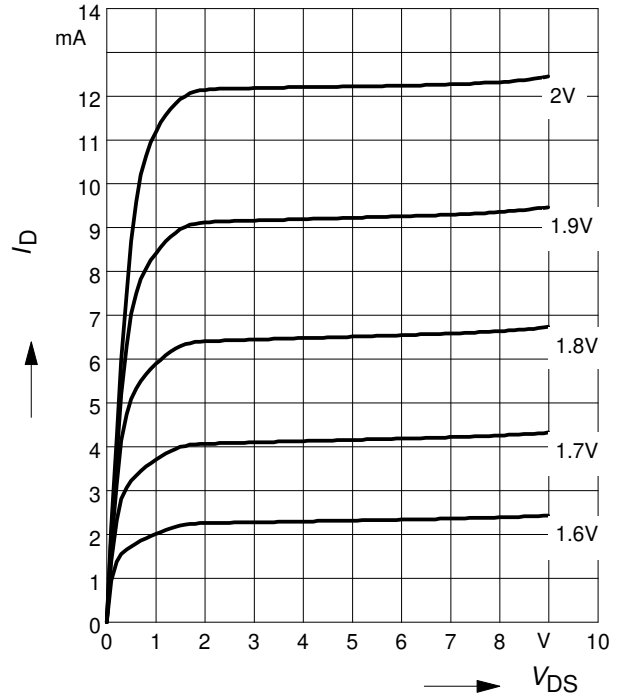
Electrical Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics - (verified by random sampling)					
Forward transconductance $V_{DS} = 5\text{ V}$, $V_{G2S} = 4\text{ V}$	g_{fs}	-	33	-	mS
Gate1 input capacitance $V_{DS} = 5\text{ V}$, $V_{G2S} = 4\text{ V}$, $f = 10\text{ MHz}$	C_{g1ss}	-	1.9	-	pF
Output capacitance $V_{DS} = 5\text{ V}$, $V_{G2S} = 4\text{ V}$, $f = 10\text{ MHz}$	C_{dss}	-	1.1	-	
Power gain (self biased) $V_{DS} = 5\text{ V}$, $V_{G2S} = 4\text{ V}$, $f = 800\text{ MHz}$ $V_{DS} = 5\text{ V}$, $V_{G2S} = 4\text{ V}$, $f = 45\text{ MHz}$	G_p	-	24 31	-	dB
Noise figure (self biased) $V_{DS} = 5\text{ V}$, $V_{G2S} = 4\text{ V}$, $f = 800\text{ MHz}$ $V_{DS} = 5\text{ V}$, $V_{G2S} = 4\text{ V}$, $f = 45\text{ MHz}$	F	-	1.3 1.7	-	
Gain control range $V_{DS} = 5\text{ V}$, $V_{G2S} = 4...0\text{ V}$, $f = 800\text{ MHz}$	ΔG_p	45	-	-	
Cross-modulation $k=1\%$, $f_w=50\text{MHz}$, $f_{unw}=60\text{MHz}$ $AGC = 0\text{ dB}$ $AGC = 10\text{ dB}$ $AGC = 40\text{ dB}$	X_{mod}	90 - 96	- 87 100	-	-

Total power dissipation $P_{tot} = f(T_S)$



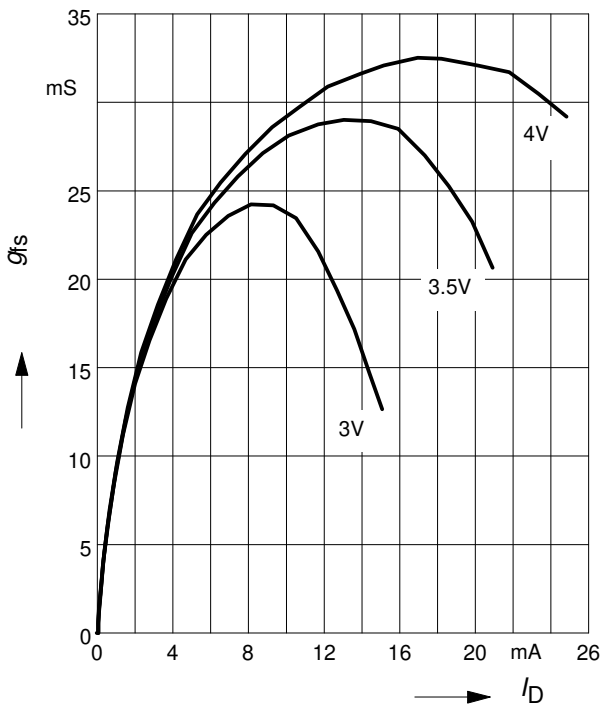
Output characteristics $I_D = f(V_{DS})$



Gate 1 forward transconductance $g_{fs} = f(I_D)$

$g_{fs} = f(I_D)$

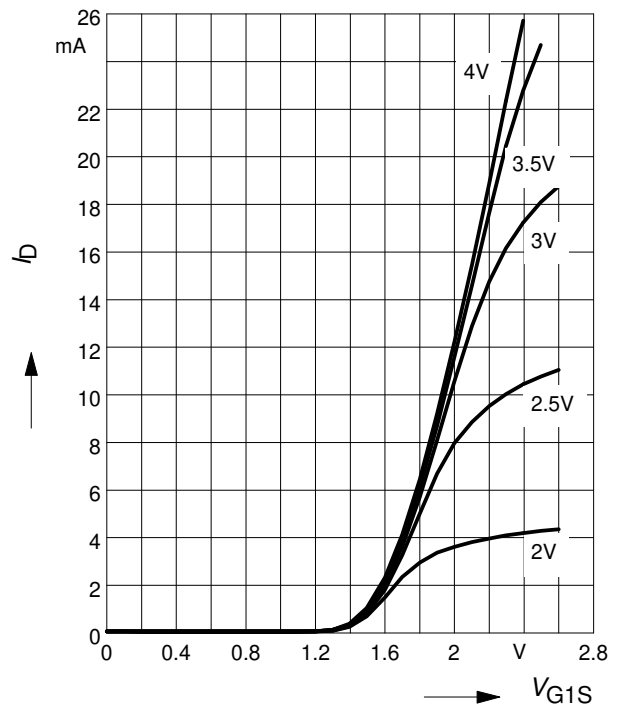
$V_{DS} = 5V, V_{G2S} = \text{Parameter}$



Drain current $I_D = f(V_{G1S})$

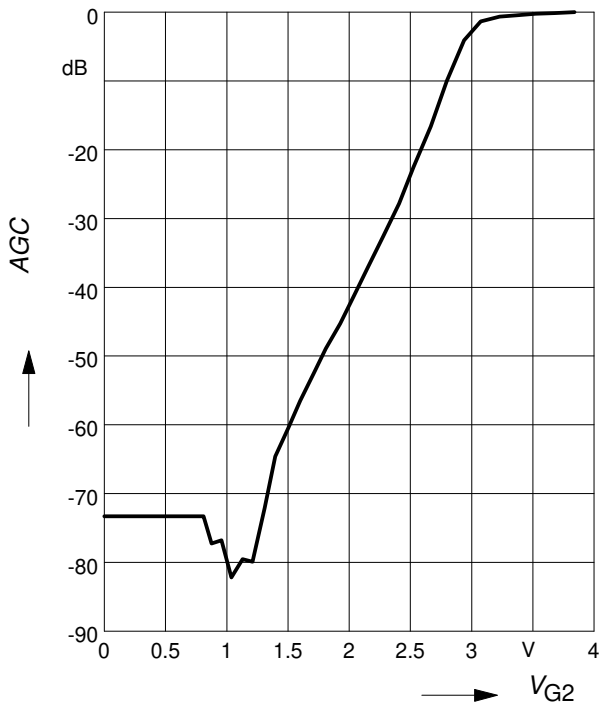
$V_{DS} = 5V$

$V_{G2S} = \text{Parameter}$



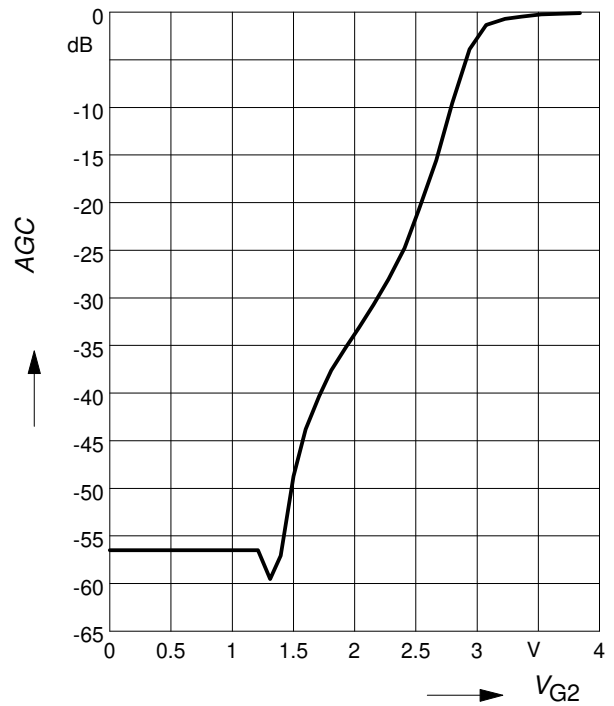
AGC characteristic $AGC = f(V_{G2S})$

$f = 200 \text{ MHz}$



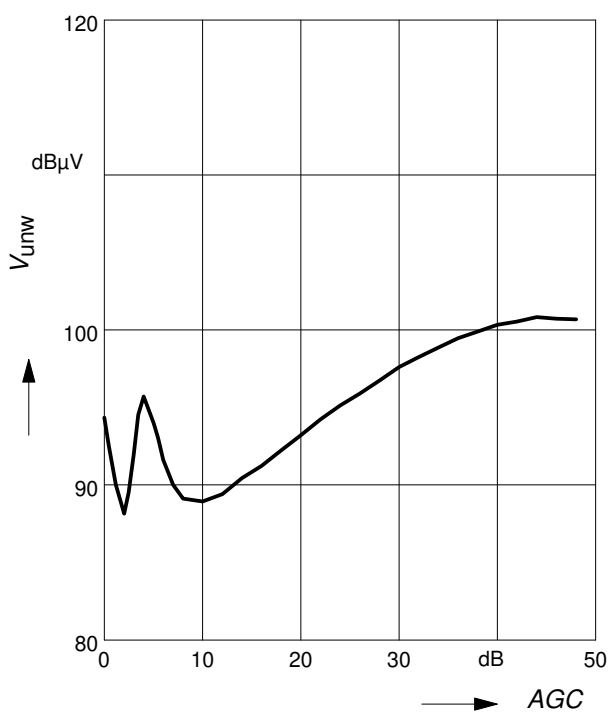
AGC characteristic $AGC = f(V_{G2S})$

$f = 800 \text{ MHz}$

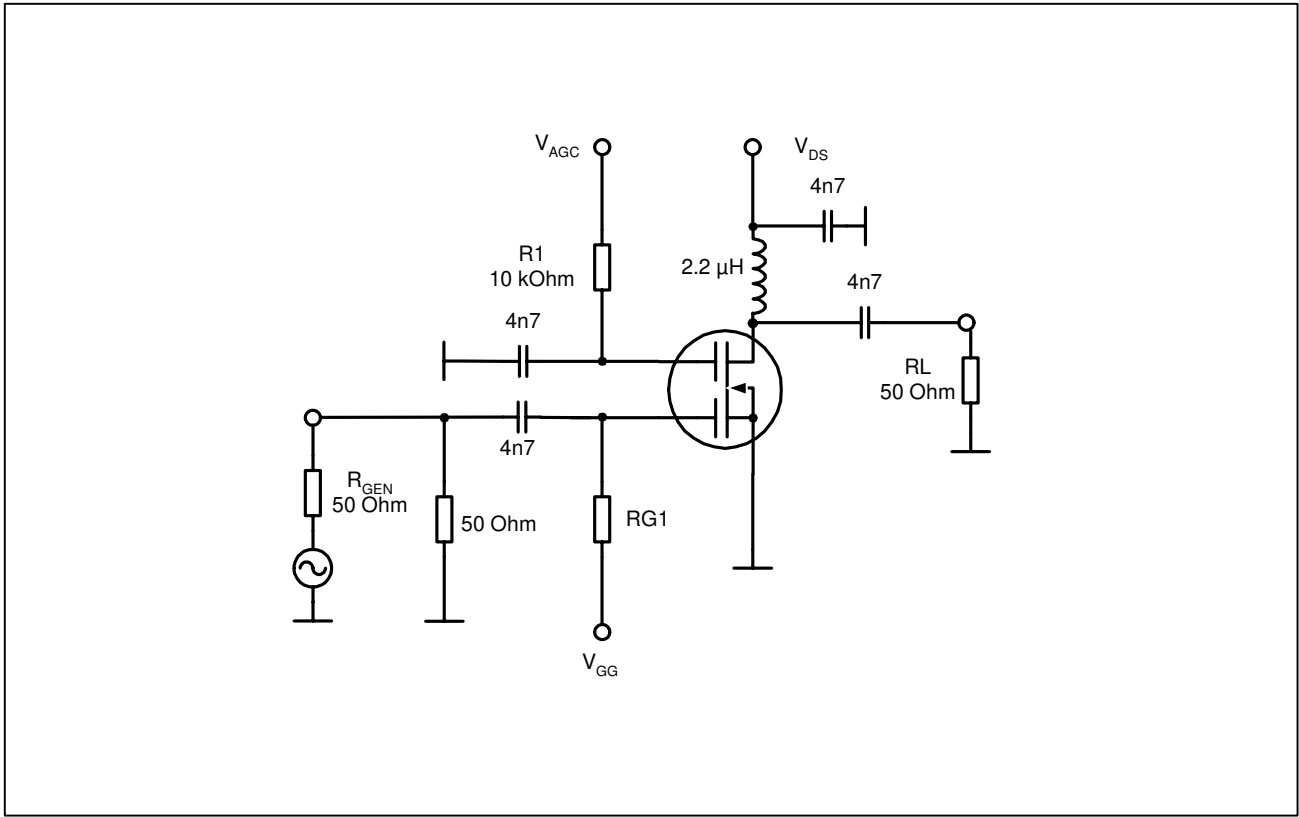


Crossmodulation $V_{unw} = (AGC)$

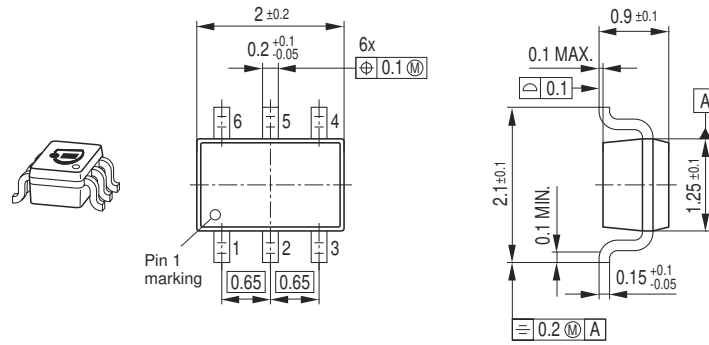
$V_{DS} = 5 \text{ V}, R_{g1} = 68 \text{ k}\Omega$



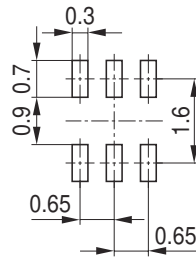
Crossmodulation test circuit



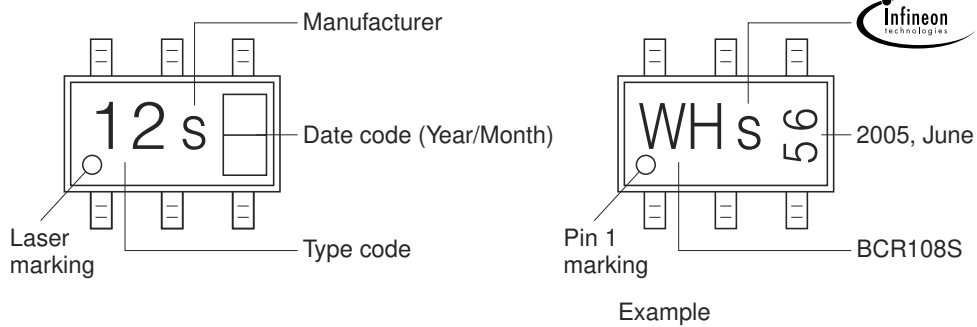
Package Outline



Foot Print

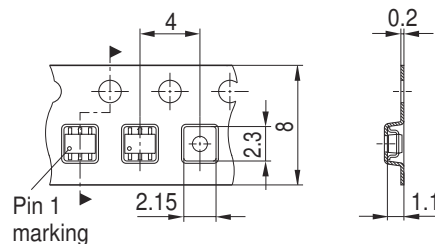


Marking Layout



Standard Packing

Reel \varnothing 180 mm = 3.000 Pieces/Reel
 Reel \varnothing 330 mm = 10.000 Pieces/Reel



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